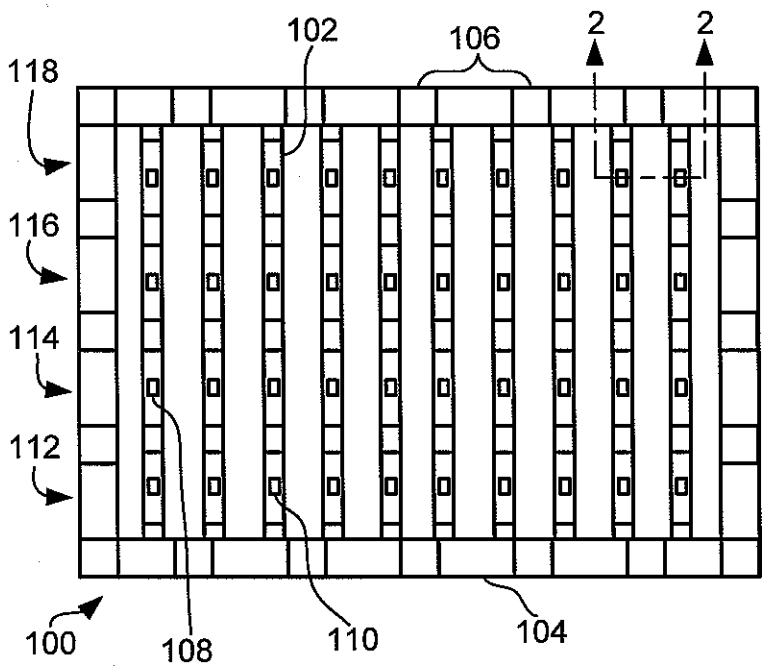
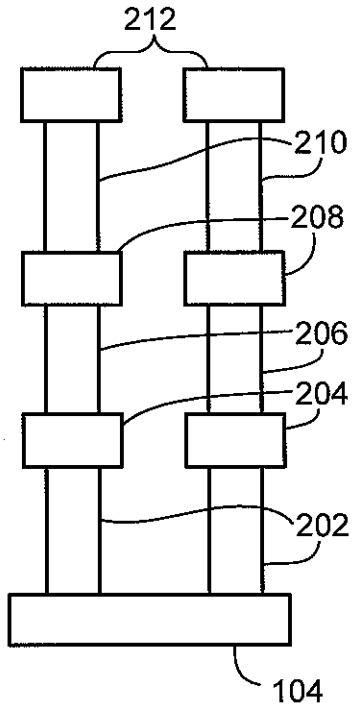


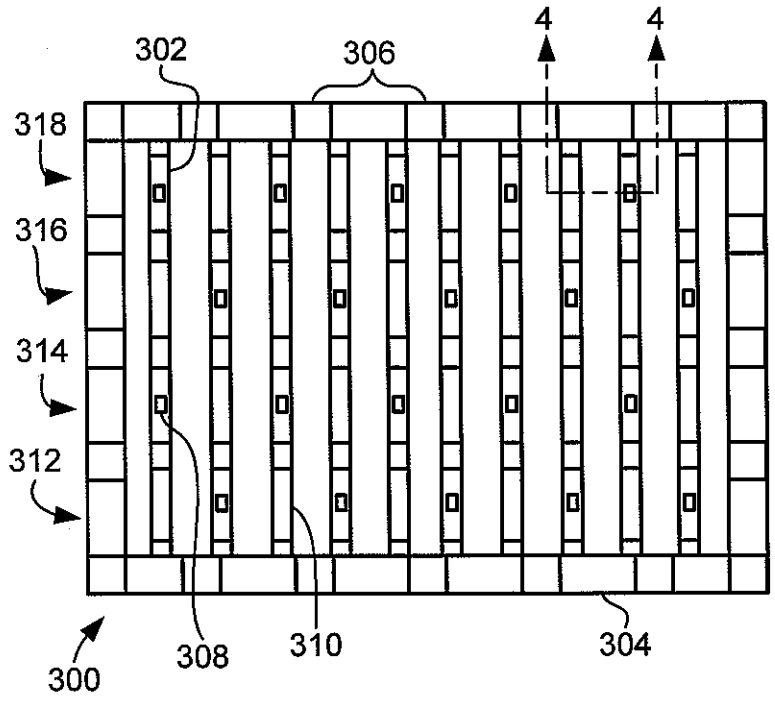
PRIOR ART

FIG. 1



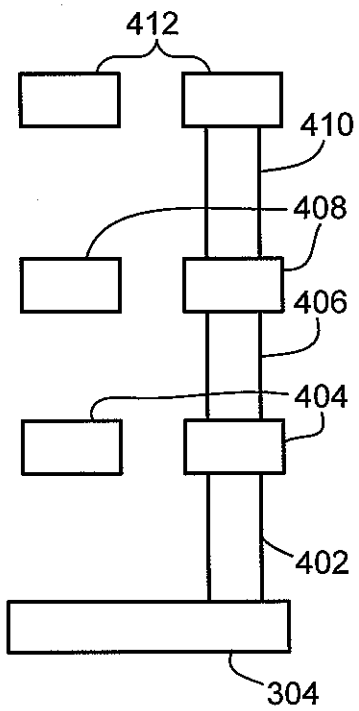
PRIOR ART

FIG. 2



PRIOR ART

FIG. 3



PRIOR ART

FIG. 4

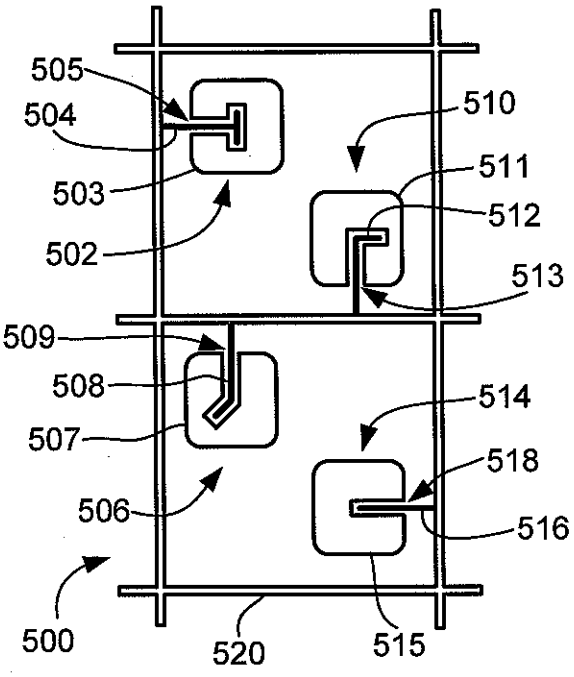


FIG. 5

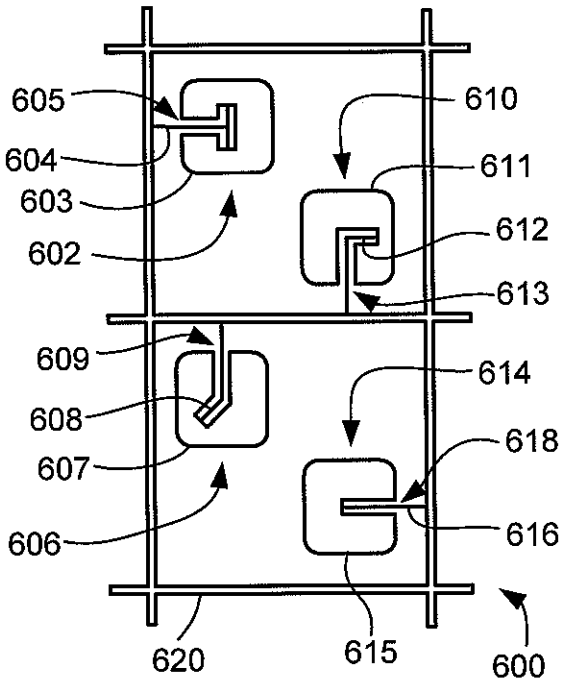


FIG. 6

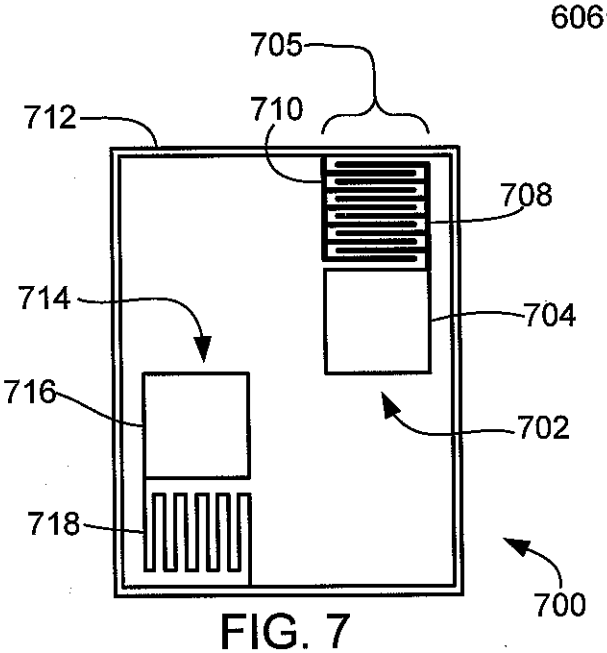


FIG. 7

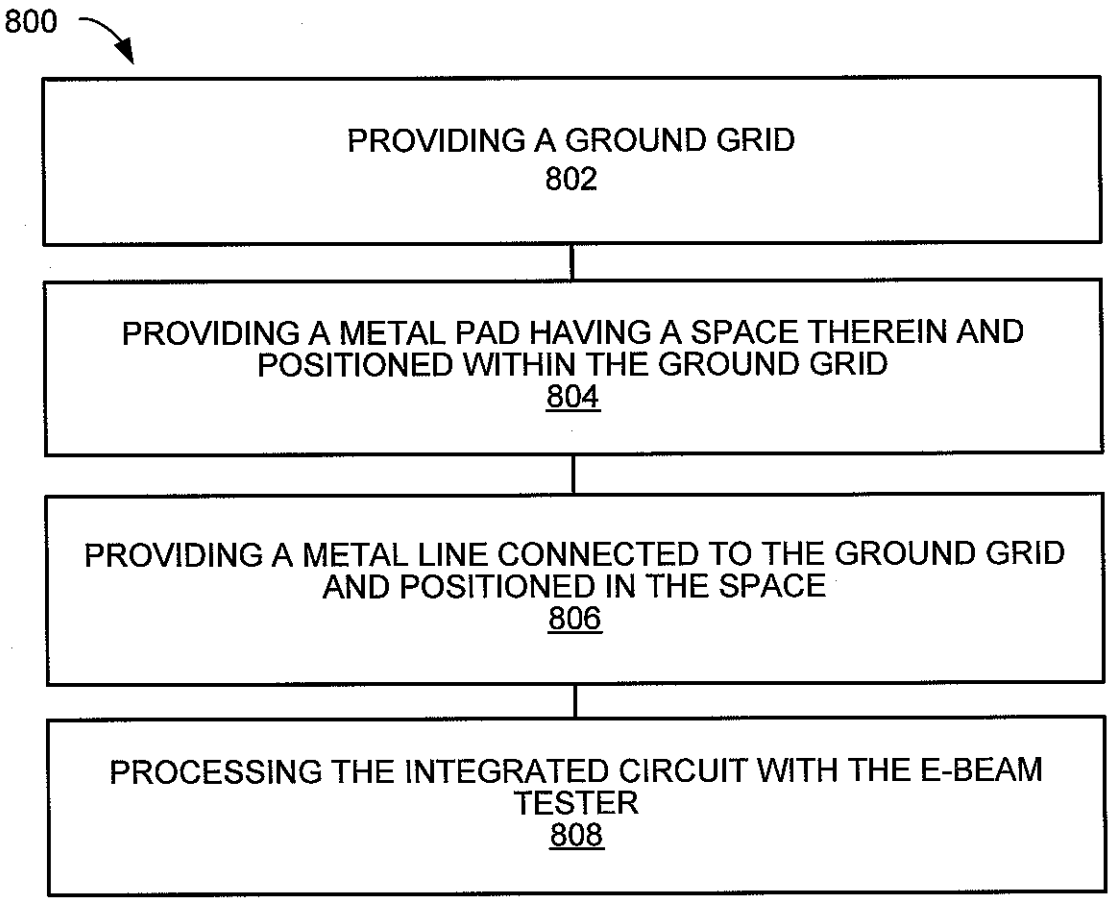

800
PROVIDING A GROUND GRID
802
PROVIDING A METAL PAD HAVING A SPACE THEREIN AND POSITIONED WITHIN THE GROUND GRID
804
PROVIDING A METAL LINE CONNECTED TO THE GROUND GRID AND POSITIONED IN THE SPACE
806
PROCESSING THE INTEGRATED CIRCUIT WITH THE E-BEAM TESTER
808

FIG. 8